



Final Product Change Notification

201802006F01

Issue Date: 11-Oct-2018
Effective Date: 08-Jan-2019

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QUALITY

Management Summary

Assembly transfer of the MMA845x from Carsem Malaysia to ASE-Chungli Taiwan (ASECL) assembly site for continuous customer supply.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

MMA845x Assembly Transfer from Carsem Malaysia to ASECL Taiwan

Description of Change

NXP Semiconductors announces the assembly transfer of MMA845x to ASE-Chungli Taiwan (ASECL) assembly site. These products are currently being assembled at the Carsem Malaysia assembly site.

With this change, NXP Semiconductors also announces the materials change to Gold Palladium Copper (AuPdCu) wire, Sumitomo EME-G700LA version P mold compound, Ablestik Die Attach Film (DAF) ATB-125 and Mitsui Rough Palladium Pre-plated Frame (PPF) with Nickel Palladium Gold (NiPdAu) C7025 material for MMA845x. These products were previously assembled with Gold (Au) wire, Sumitomo EME-G770HCD mold compound, Henkel 8006NS Screen Print DAF and HDS PPF (RT micro NiPdAuAg) C7025 material.

Reason for Change

The transfer to ASECL is for consolidation of our assembly sites. The transfer from Gold to Gold Palladium

Copper wire is an alignment to industry standard convention for wirebond material type. The change to mold compound and die attach material for QFN 3x3 package is required to standardize the bill of materials for ASECL assembly production.

Identification of Affected Products

Top side marking

There is no change to the orderable part numbers. NXP will have traceability of the assembly site by the 1st and 2nd digit of the tracecode.

Product Availability

Sample Information

Samples are available from 02-Nov-2018

Production

Planned first shipment 03-Jan-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 09-Nov-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Michelle Kelsey
Position Product Line Manager
e-mail address michelle.kelsey@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MMA8451QR1	935310199167	MMA8451QR1	low g 3-Axis 14bt ex vlt	SOT1676-1	VQFN16	RFS	BL Sensors
MMA8451QT	935322975157	MMA8451QT	low g 3-Axis 14bt ex vlt	SOT1676-1	VQFN16	RFS	BL Sensors
MMA8452QT	935317182157	MMA8452QT	low g 3-Axis 12bt ex vlt	SOT1676-1	VQFN16	RFS	BL Sensors
MMA8452QR1	935325497167	MMA8452QR1	low g 3-Axis 12bt ex vlt	SOT1676-1	VQFN16	RFS	BL Sensors
MMA8453QT	935319547157	MMA8453QT	lw g 3-Axis 10bt w/exp V	SOT1676-1	VQFN16	RFS	BL Sensors
MMA8453QR1	935310197167	MMA8453QR1	lw g 3-Axis 10bt w/exp V	SOT1676-1	VQFN16	RFS	BL Sensors